

**AMENDMENTS TO THE CLAIMS**

1-2. (Cancelled)

3.\_\_\_\_(Currently Amended) ~~A method comprising: The method of Claim 1 wherein~~  
~~said image sensor die uses a ball grid array (BGA) on the underside of said die.~~  
forming a plurality of image sensor die having micro-lenses onto a semiconductor  
wafer, wherein said image sensor die uses a ball grid array (BGA) on the  
underside of said die;  
forming a protective layer over said image sensor die;  
dicing said wafer to separate said plurality of image sensor die;  
mounting said image sensor die onto an integrated circuit package; and  
removing said protective layer from said image sensor die.

4-5. (Cancelled)